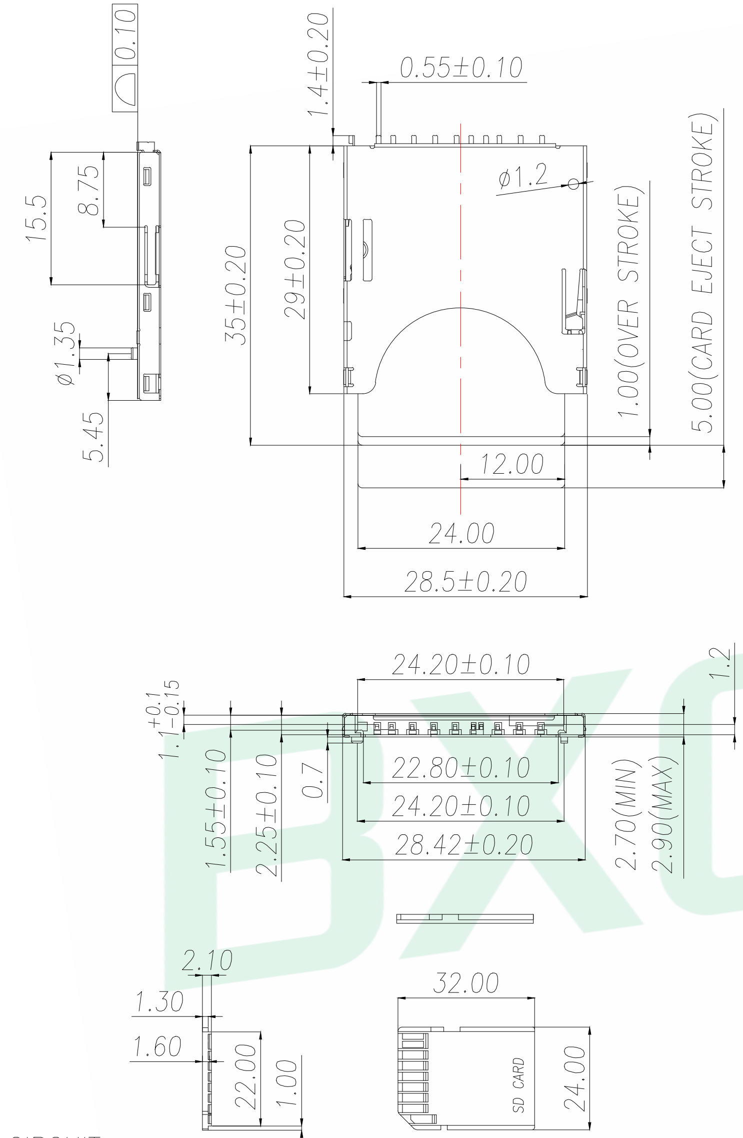
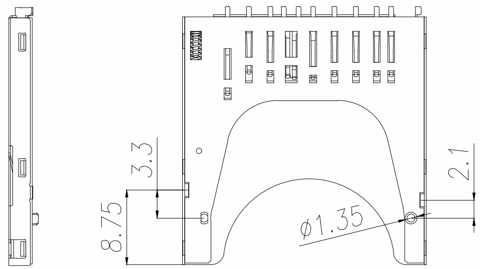
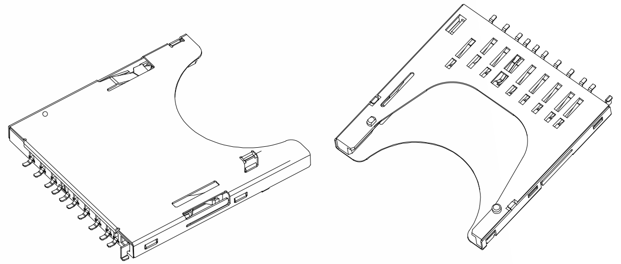
REV.	DESCRIPTION	ECN NO.	NAME	DATE





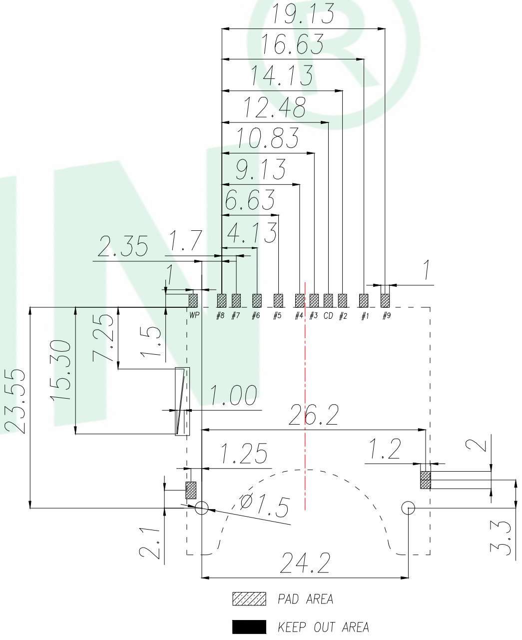


NOTES:

1.MATERIAL:
- HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V_0,COLOR:BLACK.
- CONTACT: COPPER ALLOYS.
- COVER: COPPER ALLOYS OR STEEL.

2.PLATING:
- UNDERPLATE: NICKEL.
- CONTACT AREA: GOLD OVER NICKEL.
- SOLDER AREA: TIN OVER NICKEL.

3.MULTIMEDIA CARD COMPATIBLE



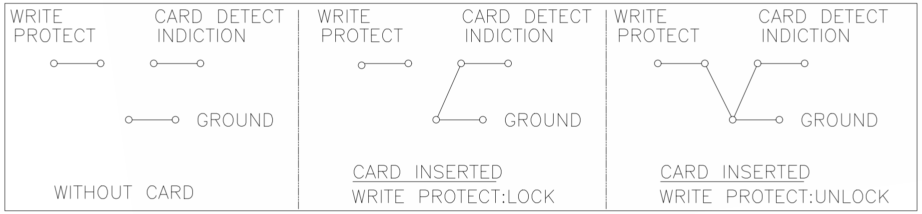
RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ±0.05

SD CARD PIN DEFINE

Pin#	Name	Type	Description
1	CD/DAT3	I/O/PP	Card Detelct/ Date Line[Bit3]
2	CMD	PP	Command/Response
3	Vss1	S	Supply voltage ground
4	VDD	S	Supply voltage
5	CLK	I	Clock
6	Vss2	S	Supply voltage ground
7	DAT0	I/O/PP	Date Line [Bit0]
8	DAT1	I/O/PP	Date Line [Bit1]
9	DAT2	I/O/PP	Date Line [Bit2]
10	CD		CARD DETECT
11	WP		WRITE PROTECT

CIRCUIT:



GENERAL TOLERANCE

DIM.	TOL.
X.X:	±0.35
X.XX:	±0.25
X.XXX:	±0.15
GENERAL ANGLE:	
X.X°:	±5°
X.XX°:	±3°

DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD

BXCONN®

TITLE: SD CARD CONN PUSH SMT

DWG. NO.: SD-TD11P

CHECKED: MAX

PART NO.: SD-TD11P

DRAWN: ELLA

UNIT: mm

SCALE: none

SHEET: 1of 1

DWG. SIZE: A4

LAYER: bxconn

APPROVED: WILL